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•	State-of-the-Art Advanced BiCMOS Technology (ABT) Widebus™ Design for	SN54ALVTHR16245 WD PACKAGE SN74ALVTHR16245 DGG, DGV, OR DL PACKAGE
	2.5-V and 3.3-V Operation and Low Static-Power Dissipation	
•	Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V <sub>CC</sub> )	1B1 2 47 1 1A1 1B2 3 46 1 1A2
•	Typical V <sub>OLP</sub> (Output Ground Bounce) <0.8 V at V <sub>CC</sub> = 3.3 V, T <sub>A</sub> = 25°C	GND 4 45 GND 1B3 5 44 1A3 1B4 6 43 1A4
٠	High Drive (–12/12 mA at 3.3-V V <sub>CC</sub> )	V <sub>CC</sub> [] 7 42 [] V <sub>CC</sub>
•	I <sub>off</sub> and Power-Up 3-State Support Hot Insertion	1B5 0 8 41 0 1A5 1B6 0 9 40 0 1A6
•	Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating	GND 0 10 39 GND 1B7 11 38 1A7 1B8 12 37 1A8
•	Output Ports Have Equivalent 30- $\Omega$ Series Resistors, So No External Resistors Are Required	2B1 13 36 2A1 2B2 14 35 2A2 GND 15 34 GND
•	Flow-Through Architecture Facilitates Printed Circuit Board Layout	2B3   16 33   2A3 2B4   17 32   2A4 V <sub>CC</sub>   18 31   V <sub>CC</sub>
•	Distributed V <sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise	2B5 [ 19 30 ] 2A5 2B6 [ 20 29 ] 2A6
•	Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II	GND 21 28 GND 2B7 22 27 2A7
•	ESD Protection Exceeds JESD 22 – 2000-V Human-Body Model (A114-A) 200 V Machine Model (A115 A)	2B8 23 26 2A8 2DIR 24 25 20E

- 200-V Machine Model (A115-A)
- 1000-V Charged-Device Model (C101)

### description/ordering information

The 'ALVTHR16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for 2.5-V or 3.3-V  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

TA	PACKA	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tape and reel	SN74ALVTHR16245LR	ALVTHR16245
1000 1- 0500	TSSOP – DGG	Tape and reel	SN74ALVTHR16245GR	ALVTHR16245
–40°C to 85°C	TVSOP – DGV	Tape and reel	SN74ALVTHR16245VR	TR245
	VFBGA – GQL	Tape and reel	SN74ALVTHR16245KR	TR245
–55°C to 125°C	CFP – WD	Tube	SNJ54ALVTHR16245W	SNJ54ALVTHR16245W

### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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### description/ordering information (continued)

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

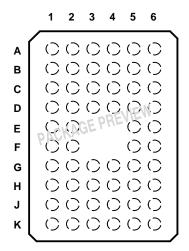
All outputs are designed to sink up to 12 mA, and include equivalent  $30-\Omega$  resistors to reduce overshoot and undershoot.

These devices are fully specified for hot-insertion applications using I<sub>off</sub> and power-up 3-state. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When  $V_{CC}$  is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### SN74ALVTHR16245 ... GQL PACKAGE (TOP VIEW)



### terminal assignments

	1	2	3 4		5	6
Α	1DIR	NC	NC	NC	NC	1 <mark>0E</mark>
в	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	VCC	VCC	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
н	2B5	2B6	V <sub>CC</sub>	V <sub>CC</sub>	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
κ	2DIR	NC	NC	NC	NC	2 <mark>0E</mark>

NC - No internal connection

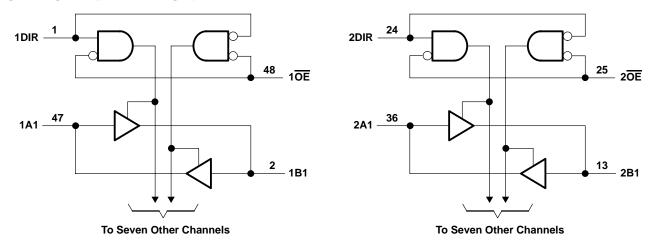
#### **FUNCTION TABLE** (each 8-bit section)

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	н	A data to B bus
н	Х	Isolation



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### logic diagram (positive logic)



Pin numbers shown are for the DGG, DGV, DL, and WD packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> 0.5	5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	).5 V to 7 V
Voltage range applied to any output in the high or power-off state, V <sub>O</sub> (see Note 1)C	).5 V to 7 V
Output current in the low state, I <sub>O</sub> : SN54ALVTHR16245	96 mA
SN74ALVTHR16245	128 mA
Output current in the high state, I <sub>O</sub> : SN54ALVTHR16245	–48 mA
SN74ALVTHR16245	–64 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	
DGV package	58°C/W
DL package	63°C/W
GQL package	42°C/W
Storage temperature range, T <sub>stg</sub> 65°	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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## recommended operating conditions, V\_CC = 2.5 V $\pm$ 0.2 V (see Note 3)

			SN54ALVTHR16245			SN74A	LVTHR	6245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2.3		2.7	2.3		2.7	V	
VIH	High-level input voltage	1.7		h	1.7			V	
VIL	Low-level input voltage		Vin	0.7			0.7	V	
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
ЮН	High-level output current			1	-6			-8	mA
IOL	Low-level output current			5	6			12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	20,	4	10			10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## recommended operating conditions, V<sub>CC</sub> = 3.3 V $\pm$ 0.3 V (see Note 3)

			SN54A		16245	SN74A	LVTHR	16245	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage	3		3.6	3		3.6	V	
VIH	High-level input voltage	2		h	2			V	
VIL	Low-level input voltage			Vin	0.8			0.8	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
ЮН	High-level output current			1	-8			-12	mA
IOL	Low-level output current			5	8			12	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled	20,		10			10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### electrical characteristics over recommended operating free-air temperature range, $V_{CC}$ = 2.5 V ± 0.2 V (unless otherwise noted)

PARAMETER		TEST		SN54/	LVTHR	16245	SN74	<b>LVTHR</b>	16245	
Ρ.	ARAMETER	TEST C	ONDITIONS	MIN	түр†	MAX	MIN	TYP <sup>†</sup>	MAX	UNII
VIK		V <sub>CC</sub> = 2.3 V,	lj = –18 mA			-1.2			-1.2	V
		$V_{CC}$ = 2.3 V to 2.7 V,	I <sub>OH</sub> = –100 μA	V <sub>CC</sub> –0	.2		VCC-0	.2		
Vон			I <sub>OH</sub> = -6 mA	1.7						V
		V <sub>CC</sub> = 2.3 V	I <sub>OH</sub> =8 mA				1.7			
		$V_{CC}$ = 2.3 V to 2.7 V,	I <sub>OL</sub> = 100 μA			0.2			0.2	
VOL			I <sub>OL</sub> = 6 mA			0.7				V
		V <sub>CC</sub> = 2.3 V	I <sub>OL</sub> = 12 mA						0.7	
	Control inputo	V <sub>CC</sub> = 2.7 V,	$V_I = V_{CC} \text{ or } GND$			±1			±1	
Ιį	Control inputs	V <sub>CC</sub> = 0 or 2.7 V,	V <sub>I</sub> = 5.5 V			10			10	
			V <sub>I</sub> = 5.5 V			20			20	μΑ
	A or B ports	V <sub>CC</sub> = 2.7 V	$V_I = V_{CC}$		Viv.	1			1	
			V <sub>I</sub> = 0		25	-5			-5	
l <sub>off</sub>		$V_{CC} = 0,$	$V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$		7				±100	μA
I <sub>BHL</sub> ‡		V <sub>CC</sub> = 2.3 V,	V <sub>I</sub> = 0.7 V		5 115			115		μΑ
IBHH <sub>{</sub>		V <sub>CC</sub> = 2.3 V,	V <sub>I</sub> = 1.7 V	Č.	-10			-10		μA
BHLC	P	V <sub>CC</sub> = 2.7 V,	$V_I = 0$ to $V_{CC}$	300			300			μA
IBHHO	D <sup>#</sup>	V <sub>CC</sub> = 2.7 V,	$V_I = 0$ to $V_{CC}$	-300			-300			μΑ
IEX		V <sub>CC</sub> = 2.3 V,	V <sub>O</sub> = 5.5 V			125			125	μΑ
I <sub>OZ(P</sub>	U/PD) <sup>☆</sup>	$V_{CC} \le 1.2 \text{ V}, V_O = 0.5 \text{ V}$ V <sub>I</sub> = GND or V <sub>CC</sub> , OE =	/ to V <sub>CC</sub> , don't care			±100			±100	μA
		V <sub>CC</sub> = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
ICC		IO = 0,	Outputs low		2.5	4.5		2.5	4.5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V <sub>CC</sub> = 2.5 V,	V <sub>I</sub> = 2.5 V or 0		3.5			3.5		pF
C <sub>io</sub>		V <sub>CC</sub> = 2.5 V,	V <sub>O</sub> = 2.5 V or 0		8			8		pF

<sup>†</sup> All typical values are at  $V_{CC}$  = 2.5 V,  $T_A$  = 25°C. <sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at  $V_{IL}$  max.  $I_{BHL}$  should be measured after lowering  $V_{IN}$  to GND and then raising it to VIL max.

§ The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

 $\P$  An external driver must source at least IBHLO to switch this node from low to high.

<sup>#</sup> An external driver must sink at least  $I_{BHHO}$  to switch this node from high to low.

I Current into an output in the high state when  $V_O > V_{CC}$ 

\* High-impedance state during power up or power down



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# electrical characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

		теот с		SN54AL	VTHR1	6245	SN74A	LVTHR	16245		
Р	ARAMETER	IESIC	ONDITIONS	MIN T	YP†	MAX	MIN	ΜΙΝ ΤΥΡ <sup>†</sup> ΜΑΧ		UNIT	
VIK		V <sub>CC</sub> = 3 V,	lj = –18 mA			-1.2			-1.2	V	
		V <sub>CC</sub> = 3 V to 3.6 V,	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> -0.2			V <sub>CC</sub> -0.	2			
Vон			I <sub>OH</sub> = -8 mA	2						V	
		V <sub>CC</sub> = 3 V	I <sub>OH</sub> = -12 mA			2					
		$V_{CC} = 3 V \text{ to } 3.6 V,$	I <sub>OL</sub> = 100 μA			0.2			0.2		
VOL		V <sub>CC</sub> = 3 V	I <sub>OL</sub> = 8 mA			0.8				V	
		VCC = 2 V	I <sub>OL</sub> = 12 mA				0.8				
	Control inputs	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC} \text{ or } GND$			±1			±1		
	Control inputs	V <sub>CC</sub> = 0 or 3.6 V,	V <sub>I</sub> = 5.5 V			10			10		
IJ			V <sub>I</sub> = 5.5 V			20			20	μA	
	A or B ports	V <sub>CC</sub> = 3.6 V	$V_{I} = V_{CC}$		VIL	1			1	1	
			$V_{I} = 0$		RE	-5			-5		
l <sub>off</sub>		$V_{CC} = 0,$	$V_{I}$ or $V_{O}$ = 0 to 4.5 V	1	7				±100	μA	
IBHL‡	Ì	V <sub>CC</sub> = 3 V,	V <sub>I</sub> = 0.8 V	75			75			μΑ	
IBHH <sup>§</sup>	§	V <sub>CC</sub> = 3 V,	V <sub>I</sub> = 2 V	-750			-75			μA	
BHLC	P	V <sub>CC</sub> = 3.6 V,	$V_{I} = 0$ to $V_{CC}$	500			500			μA	
IBHH	0#	V <sub>CC</sub> = 3.6 V,	$V_{I} = 0$ to $V_{CC}$	-500			-500			μA	
IEX		V <sub>CC</sub> = 3 V,	V <sub>O</sub> = 5.5 V			125			125	μA	
I <sub>OZ(P</sub>	PU/PD) <sup>☆</sup>	$V_{CC} \le 1.2 \text{ V}, \text{ V}_{O} = \frac{0.5}{0.5}$ V <sub>I</sub> = GND or V <sub>CC</sub> , $\overline{OE}$	V to V <sub>CC</sub> , = don't care			±100			±100	μA	
		V <sub>CC</sub> = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1		
ICC		$I_{O} = 0,$	Outputs low		3.5	5		3.5	5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled	0.07 0.1			0.07	0.1			
$\Delta I_{CC}$		$V_{CC} = 3 V$ to 3.6 V, On Other inputs at $V_{CC}$ or				0.4			0.4	mA	
Ci		V <sub>CC</sub> = 3.3 V,	V <sub>I</sub> = 3.3 V or 0		3.5			3.5		pF	
Cio		V <sub>CC</sub> = 3.3 V,	V <sub>O</sub> = 3.3 V or 0		8			8		pF	

<sup>†</sup> All typical values are at  $V_{CC} = 3.3$  V,  $T_A = 25^{\circ}$ C.

<sup>‡</sup> The bus-hold circuit can sink at least the minimum low sustaining current at V<sub>IL</sub> max. I<sub>BHL</sub> should be measured after lowering V<sub>IN</sub> to GND and then raising it to V<sub>IL</sub> max.

§ The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to V<sub>CC</sub> and then lowering it to VIH min.

 $\P$  An external driver must source at least  $I_{BHLO}$  to switch this node from low to high.

<sup>#</sup> An external driver must sink at least  $I_{BHHO}$  to switch this node from high to low.

I Current into an output in the high state when VO > VCC

 $^{\star}$  High-impedance state during power up or power down

<sup>D</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.



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# switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF, V<sub>CC</sub> = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

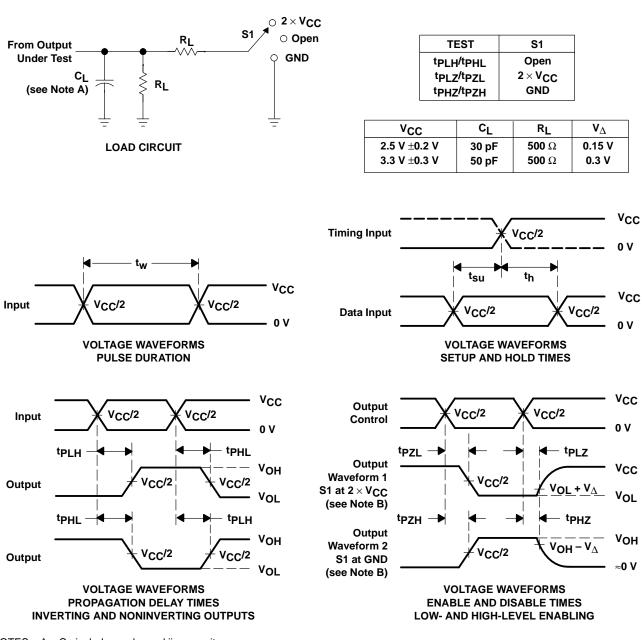
PARAMETER	FROM	то	SN54ALV	THR16245	SN74ALV	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT	
<sup>t</sup> PLH	A or B	B or A	0.5	4.3	0.5	4.3	ns	
<sup>t</sup> PHL	AUD	BOIA	0.5	3.7	0.5	3.7	115	
<sup>t</sup> PZH	ŌĒ	A or B	1.8	5.6	1.8	5.6	50	
<sup>t</sup> PZL	OE	AUB	1.6	4.7	1.6	4.7	ns	
<sup>t</sup> PHZ	ŌĒ	A or B	17	5	1.7	5	ns	
<sup>t</sup> PLZ	UE		<b>0</b> 1.4	4.4	1.4	4.4	115	

# switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF, V<sub>CC</sub> = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALV	THR16245	SN74ALV	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	ΜΑΧ	MIN	MAX	UNIT	
<sup>t</sup> PLH	A or B	B or A	0.5	3.7	0.5	3.7	ns	
<sup>t</sup> PHL	AUD	BUIA	0.5	3.9	0.5	3.9	115	
<sup>t</sup> PZH	OE	A or B	1.3	5.2	1.3	5.2	ns	
<sup>t</sup> PZL	ÜE	AUB	1.3	4	1.3	4	115	
<sup>t</sup> PHZ	ŌĒ	A or B	2	5.1	2	5.1	ns	
<sup>t</sup> PLZ	UL		21.5	4.8	1.5	4.8	113	



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVTHR16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245LRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTHR16245ZQLR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74ALVTHR16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245KR	NRND	BGA MI CROSTA R JUNI OR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74ALVTHR16245LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTHR16245VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## PACKAGE OPTION ADDENDUM



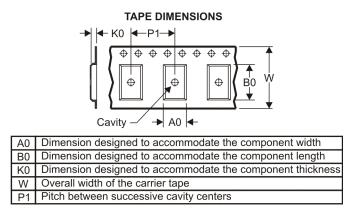
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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVTHR16245ZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
SN74ALVTHR16245GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVTHR16245KR	BGA MI CROSTA R JUNI OR	GQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
SN74ALVTHR16245LR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTHR16245VR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008

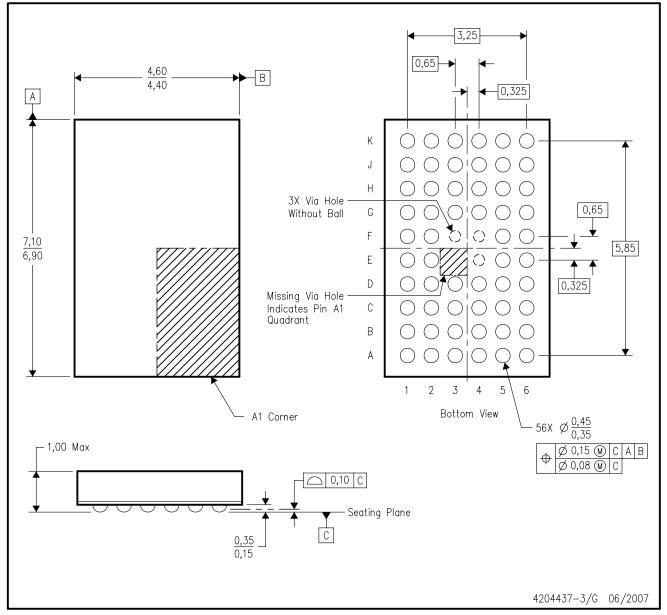


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVTHR16245ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	346.0	346.0	33.0
SN74ALVTHR16245GR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ALVTHR16245KR	BGA MICROSTAR JUNIOR	GQL	56	1000	346.0	346.0	33.0
SN74ALVTHR16245LR	SSOP	DL	48	1000	346.0	346.0	49.0
SN74ALVTHR16245VR	TVSOP	DGV	48	2000	346.0	346.0	41.0

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-285 variation BA-2.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



## **MECHANICAL DATA**

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



## **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

### DGG (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



## **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

### DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



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